

Main Product Characteristics:

Features and Benefits

Description:

Absolute Max Rating:

| Symbol | Parameter | Max. | Units |
|---------------------------|---|------|-------|
| $I_D @ T_C = 25^{\circ}C$ | Continuous Drain Current, V _{GS} @ 10V | -3.5 | A |
| I _{DM} | Pulsed Drain Current | -14 | |
| | • | · | |

 $P_D @T_C = 25^{\circ}C$



Thermal Resistance

Symbol

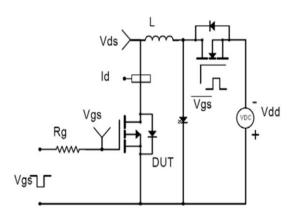
Characterizes

Typ. M(pen5E(

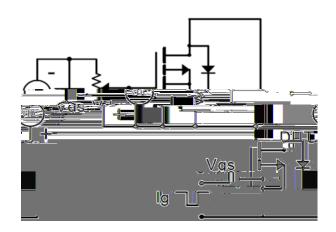


Test Circuits and Waveforms

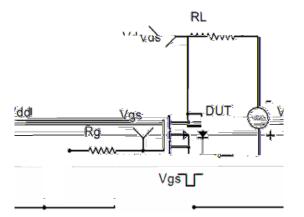
EAS Test Circuit:



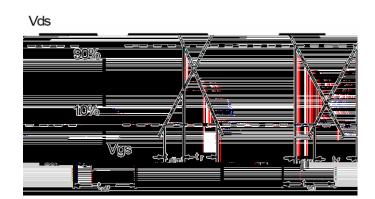
Gate Charge Test Circuit:



Switching Time Test Circuit:



Switching Waveforms:



Notes:

Calculated continuous current based on maximum allowable junction temperature.

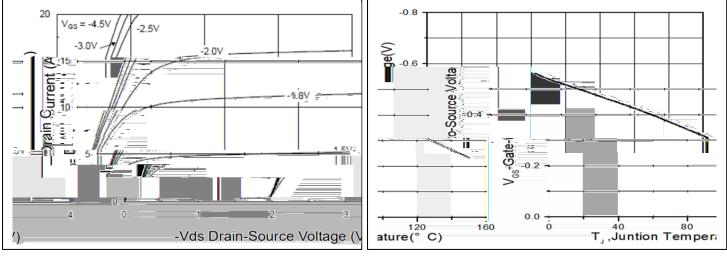
Repetitive rating; pulse width limited by max. junction temperature.

The power dissipation P_D is based on max. junction temperature, using junction-to-case thermal resistance.

The value of R $_A$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C



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Typical Electrical and Thermal Characteristics

Figure1.Typical Output Characteristics

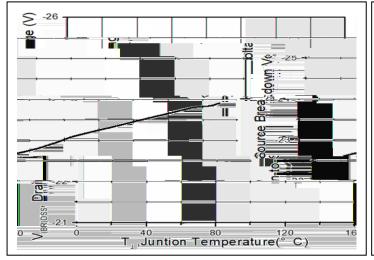


Figure3. Drain-to-Source Breakdown Voltage vs. Junction Temperature

-4.50

-3.75

ain Current (A)

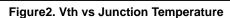
100

erature-(-C-)-

ð 1.50

140

120



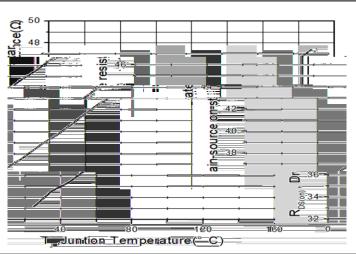


Figure4. R_{DS(on)} vs. Junction Temperature

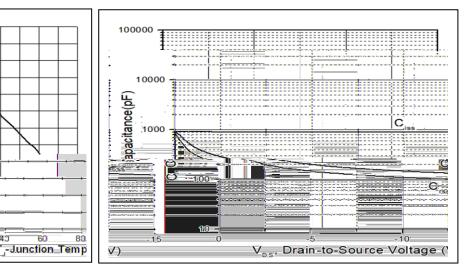


Figure5. Drain Current vs. Junction Temperature

Figure6. Capacitance

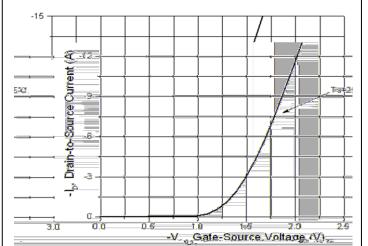
0.75

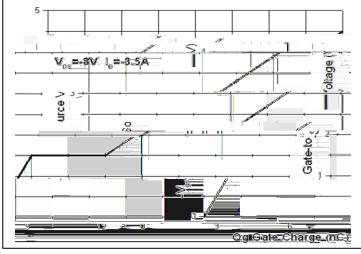
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60



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Typical Electrical and Thermal Characteristics

Figure7. Transfer Characteristics

Figure8. Gate source voltage vs. Gate Charge

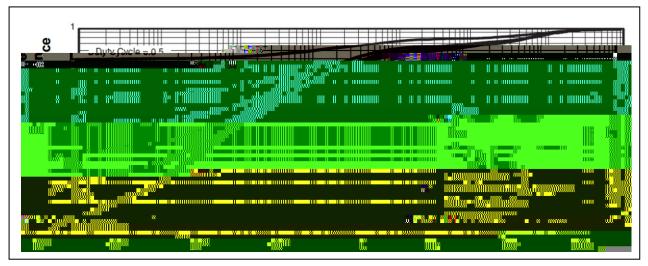
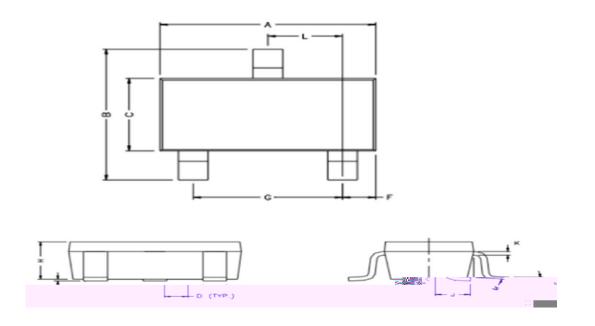


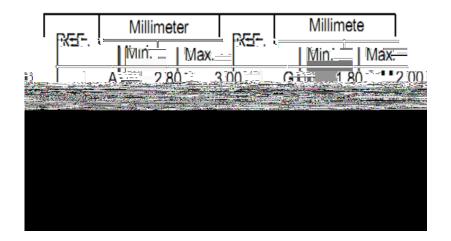
Figure9. Normalized Maximum Transient Thermal Impedance



Mechanical Data

SOT-23 Package Outline(Unit:mm)







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